

S/N 09/858238

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant:	Tee O. Chong et al.	Examiner:	John Vigushin
Serial No.:	09/858238	Group Art Unit:	2827
Filed:	May 15, 2001	Docket:	884.419US1
Title:	ELECTRONIC PACKAGE WITH HIGH DENSITY INTERCONNECT AND ASSOCIATED METHODS		

INFORMATION DISCLOSURE STATEMENT

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

In compliance with the duty imposed by 37 C.F.R. § 1.56, and in accordance with 37 C.F.R. §§ 1.97 *et. seq.*, the enclosed materials are brought to the attention of the Examiner for consideration in connection with the above-identified patent application. Applicants respectfully request that this Information Disclosure Statement be entered and the documents listed on the attached Form 1449 be considered by the Examiner and made of record. Pursuant to the provisions of MPEP 609, Applicants request that a copy of the 1449 form, initialed as being considered by the Examiner, be returned to the Applicants with the next official communication.

Pursuant to 37 C.F.R. §1.97(c)(1) and 37 C.F.R. §1.97(e)(1), Applicants state that each item of information contained in the Information Disclosure Statement was first cited in any communication from a foreign patent office in a counterpart foreign application not more than three months prior to the filing of the Information Disclosure Statement.

It is believed that no fee or statement is required with the Information Disclosure Statement. However, if a final action under §1.113, a notice of allowance under §1.311, or an action that otherwise closes prosecution in the application has been mailed, the Commissioner is hereby authorized to charge the required fees to Deposit Account No. 19-0743 in order to have this Information Disclosure Statement considered.

INFORMATION DISCLOSURE STATEMENT

Serial No :09/858238

Filing Date: May 15, 2001

Title: ELECTRONIC PACKAGE WITH HIGH DENSITY INTERCONNECT AND ASSOCIATED METHODS

Assignee: Intel Corporation

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The Examiner is invited to contact the Applicants' Representative at the below-listed telephone number if there are any questions regarding this communication.

Respectfully submitted,

TEE O. CHONG ET AL.

By their Representatives,

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Date May 28, 2003

By Ann M. McCrackin
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CERTIFICATE UNDER 37 CFR 1.8: The undersigned hereby certifies that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail, in an envelope addressed to: Commissioner of Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on this 28 day of May, 2003

Kacia Lee
Name

Kacia Lee
Signature



Substitute for form 1449A/PTO

**INFORMATION DISCLOSURE
STATEMENT BY APPLICANT**
(as many sheets as necessary)

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PTO/SB/08A(10-01)
Approved for use through 10/31/2002. OMB 551-0031
US Patent & Trademark Office: U.S. DEPARTMENT OF COMMERCE

Complete if Known

Application Number	09/858238
Filing Date	May 15, 2001
First Named Inventor	Chong, Tee
Group Art Unit	2827
Examiner Name	Vigushin, John

Sheet 1 of 1

Attorney Docket No: 884.419US1

US PATENT DOCUMENTS

Examiner Initial *	USP Document Number	Publication Date	Name of Patentee or Applicant of cited Document	Class	Subclass	Filing Date If Appropriate
	US-4,495,377	01/22/1985	Johnson, C. L., et al.	174	68.5	12/30/1982
	US-6,310,398	10/30/2001	Katz, W. M.	257	773	11/12/1999

FOREIGN PATENT DOCUMENTS

Examiner Initials*	Foreign Document No	Publication Date	Name of Patentee or Applicant of cited Document	Class	Subclass	T ²
	EP-0883182	12/09/1998	Horiuchi, M., et al.	H01L	23/523	
	EP-0921567	06/09/1999	Horiuchi, M., et al.	H01L	23/498	
	EP-0928029	07/07/1999	Horiuchi, M., et al.	H01L	23/538	
	EP-1071316	01/24/2001	Horiuchi, M., et al.	H05K	1/18	
	EP-1075026	02/07/2001	Horiuchi, M., et al.	H01L	23/498	

OTHER DOCUMENTS -- NON PATENT LITERATURE DOCUMENTS

Examiner Initials*	Cite No ¹	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published.	T ²
		DEHKORDI, P., et al., "Determination of Area-Array Bond Pitch for Optimum MCM Systems: A Case Study", <u>Proceedings of the IEEE Multi-Chip Module Conference, Los Alamitos, (Feb. 4, 1997), 8-12.</u>	
		FJELSTAD, J., "Chip Scale Packages -- Their Future Impact on PCB Design", <u>Electronic Engineering, (Mar., 1998), 75-79.</u>	

EXAMINER**DATE CONSIDERED**

Substitute Disclosure Statement Form (PTO-1449)
* EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.¹ Applicant's unique citation designation number (optional) ² Applicant is to place a check mark here if English language Translation is attached